Tender for re-opening of 3-year HKD HKSAR Institutional Government Bonds to be held on February 19

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (February 13) that a tender of 3-year HKD Government Bonds (Bonds) through the re-opening of existing 3-year Government Bond issue 03GB2710001 under the Infrastructure Bond Programme will be held on Wednesday, February 19, 2025, for settlement on Thursday, February 20, 2025.

An additional amount of HKD2.0 billion of the outstanding 3-year Bonds (issue no. 03GB2710001) will be on offer. The Bonds will mature on October 25, 2027 and will carry interest at the rate of 2.89 per cent per annum payable semi-annually in arrear. The Indicative Pricings of the Bonds on February 13, 2025 are 98.71 with an annualised yield of 3.423 per cent.

Tender is open only to Primary Dealers appointed under the Infrastructure Bond Programme. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the latest published list, which can be obtained from the Hong Kong Government Bonds website at www.hkgb.gov.hk. Each tender must be for an amount of HKD50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Hong Kong Government Bonds website, Bloomberg (GBHK <GO>) and Refinitiv (IBPGSBPINDEX). The publication time is expected to be no later than 3pm on the tender day.

HKSAR Institutional Government Bonds Tender Information

Tender information of re-opening of 3-year HKD HKSAR Institutional Government Bonds:

Issue Number : 03GB2710001

Stock Code : 4283 (HKGB 2.89 2710)

Tender Date and Wednesday, February 19, 2025

Time 9.30 am to 10.30 am

Issue and

Settlement Date : Thursday, 20 February, 2025

Amount on Offer : HKD2.0 billion

Maturity : 3 years

Remaining

maturity : Approximately 2.68 years

Maturity Date

: Monday, October 25, 2027

Interest Rate

2.89 per cent p.a. payable semi-annually

in arrear

April 24 and October 24 in each year, commencing on the Issue Date up to and including the Maturity Date, subject to adjustment in accordance with the terms of the Institutional Issuances Information

Interest Payment Dates

the Institutional Issuances Information
Memorandum of the Infrastructure Bond
Programme and Government Sustainable Bond
Programme (Information Memorandum)
published on the Hong Kong Government
Bonds website.

Method of Tender

: Competitive tender

Each competitive tender must be for an amount of HKD50,000 or integral multiples thereof. Any tender applications for the Bonds must be submitted through a Primary Dealer on the latest published list. The accrued interest to be paid by successful bidders on the issue date (February 20, 2025) for the tender amount is 471 11 and minimum denomination of

Tender Amount

is 471.11 per minimum denomination of

HKD50,000.

(The accrued interest to be paid for tender amount exceeding HKD50,000 may not be exactly equal to the figures calculated from the accrued interest per minimum denomination of HKD50,000 due to

rounding).

Please see the Information Memorandum: available on the Hong Kong Government Bonds website or approach Primary Dealers.

Other Details

Expected
commencement date
of dealing on
the Stock
Exchange
of Hong Kong
Limited

The tender amount is fully fungible with the existing 03GB2710001 (Stock code: 4283) listed on the Stock Exchange of Hong Kong.

Use of Proceeds

The Bonds will be issued under the institutional part of the Infrastructure Bond Programme. Proceeds will be invested: in infrastructure projects in accordance with the Infrastructure Bond Framework published on the Hong Kong Government Bonds website.